



Logout

Search

My Account | Products

The Delphion Integrated View: INPADOC Record

Buy Now: More choices...

Tools: Add to Work File | Create new Work

View: Jump to:

Top

Go to: Dewey

>Title:

TW0455938B: WAFER POLISHING STOP DETECTION METHOD AND POLISHING STOP DETECTION DEVICE

Country:

TW Taiwan

Kind:

B Patent

Inventor:

IDE, SATORU; , Japan
TANAKA, KIYOSHI; , Japan
ITO, TOSHIHIRO; , Japan

Assignee:

NIKON KK, Japan
[News, Profiles, Stocks and More about this company](#)

Published / Filed:

Sept. 21, 2001 / Dec. 9, 1999

Application

Number:

TW1999088121563

IPC Code:

H01L 21/304; B24B 37/04;

ECLA Code:

None

Priority Number:

Dec. 10, 1998 [JP1998000368466](#)

Abstract:

A wafer polishing stop detection method and polishing stop detection device which provides the method for detecting CMP polishing stop by polishing surface status index of polishing wafer in more precision. The solution of the wafer polishing stop detection method is irradiating the light from the light source; collecting the reflection on the color recognition sensor using fiber optics for light color component recognition; recognizing the color components of the tracing material on the pre-polished wafer using the color recognition sensor; displaying an "on" status if the color components are recognized and an "off" status if the color components are not recognized; digitally displaying the "on" and "off" periods on the horizontal axis during wafer polishing from a point (except the center) on the rotating wafer surface irradiated by the color recognition sensor; detecting the integral ($\int dm$) for the specified period for "off" pulse width in digital display so that when the detected integral ($\int dm$) can be consistent with the integral value ($\int dn$) for the specified period for "off" pulse width of predetermined best wafer polishing stop, defining it as the wafer polishing stop.



Other Abstract Info:



DERABS G2000-486551



Nominate this for